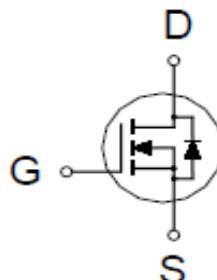
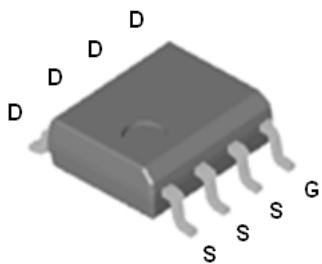


# PV6A6BA

## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
40V	9mΩ @ $V_{GS} = 10V$	10.9A



SOP-8

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	40	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_A = 25^\circ C$	$I_D$	10.9	A
			8.7	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	44	
Avalanche Current		$I_{AS}$	31	
Avalanche Energy	$L = 0.1mH$	$E_{AS}$	48	mJ
Power Dissipation	$T_A = 25^\circ C$	$P_D$	2.2	W
			1.4	
Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		55	°C / W
Junction-to-Case	$R_{\theta JC}$		25	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ .

## PV6A6BA N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

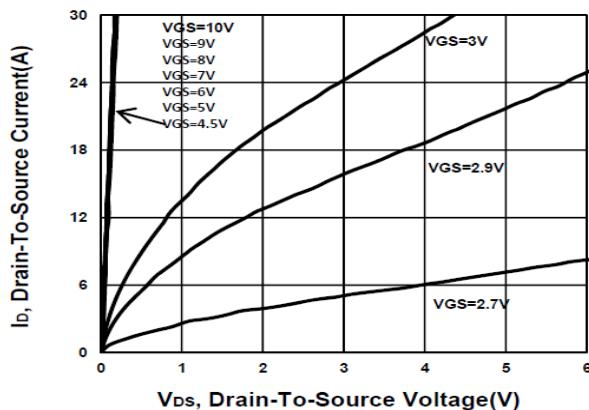
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.7	2.3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		6.8	14	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		6	9	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 10\text{A}$		71		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 20\text{V}, f = 1\text{MHz}$		1685		pF
Output Capacitance	$C_{\text{oss}}$			227		
Reverse Transfer Capacitance	$C_{\text{rss}}$			129		
Gate Resistance	$R_g$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.3		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_g(V_{\text{GS}}=10\text{V})$	$V_{\text{DS}} = 20\text{V}, I_D = 10\text{A}$		33		nC
	$Q_g(V_{\text{GS}}=4.5\text{V})$			17		
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			4.4		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			8		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d(on)}}$	$V_{\text{DS}} = 20\text{V}, I_D \approx 10\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		18		nS
Rise Time <sup>2</sup>	$t_r$			12		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d(off)}}$			55		
Fall Time <sup>2</sup>	$t_f$			11		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				1.6	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 10\text{A}, V_{\text{GS}} = 0\text{V}$			1.3	V
Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		13		nS
Diode Reverse Recovery Charge	$Q_{\text{rr}}$			2.5		nC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300\text{ }\mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

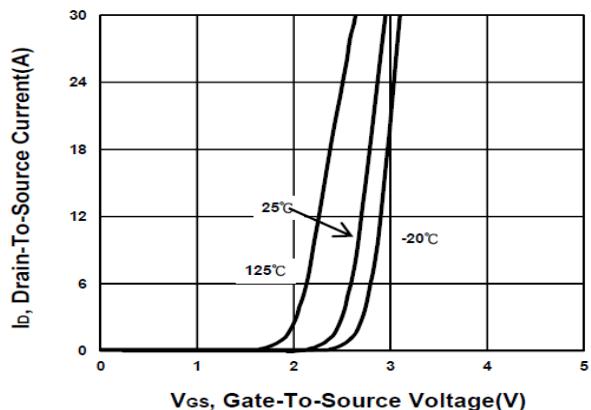
<sup>2</sup>Independent of operating temperature.

## PV6A6BA N-Channel Enhancement Mode MOSFET

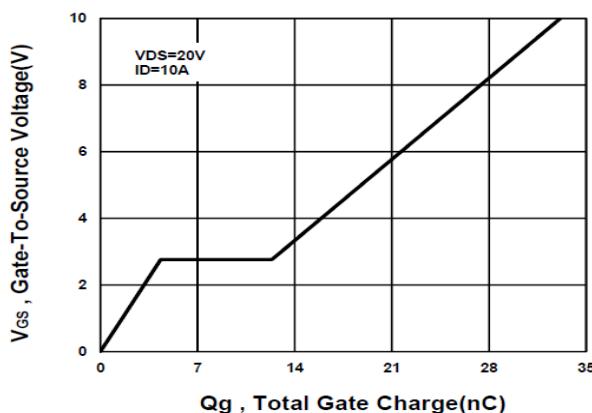
**Output Characteristics**



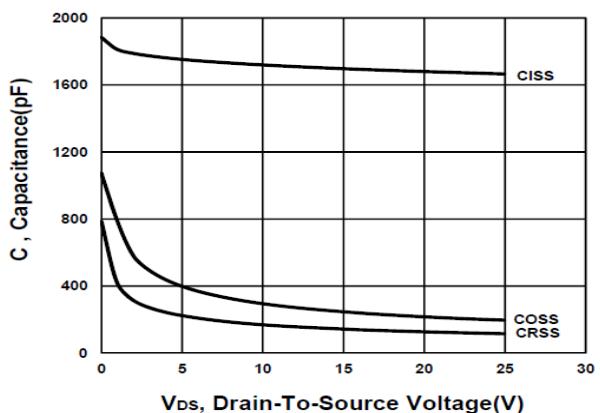
**Transfer Characteristics**



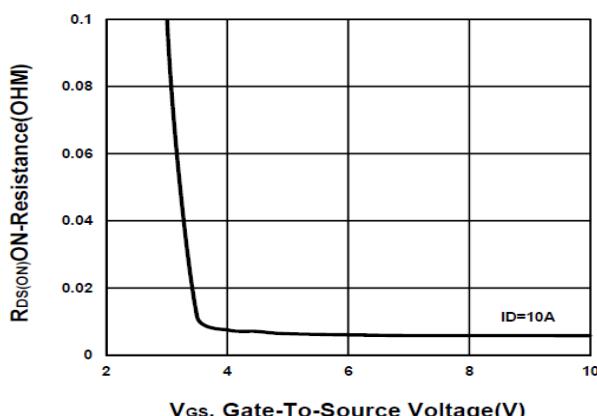
**Gate charge Characteristics**



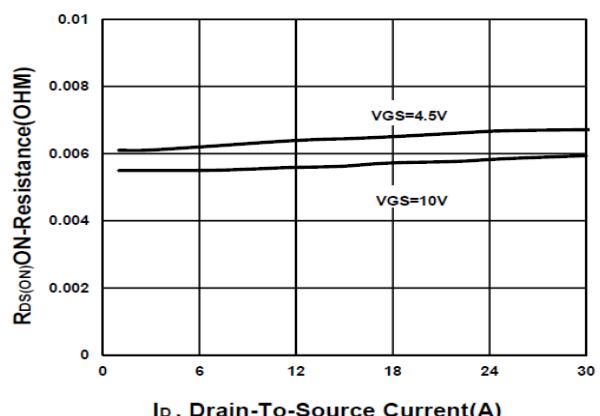
**Capacitance Characteristic**



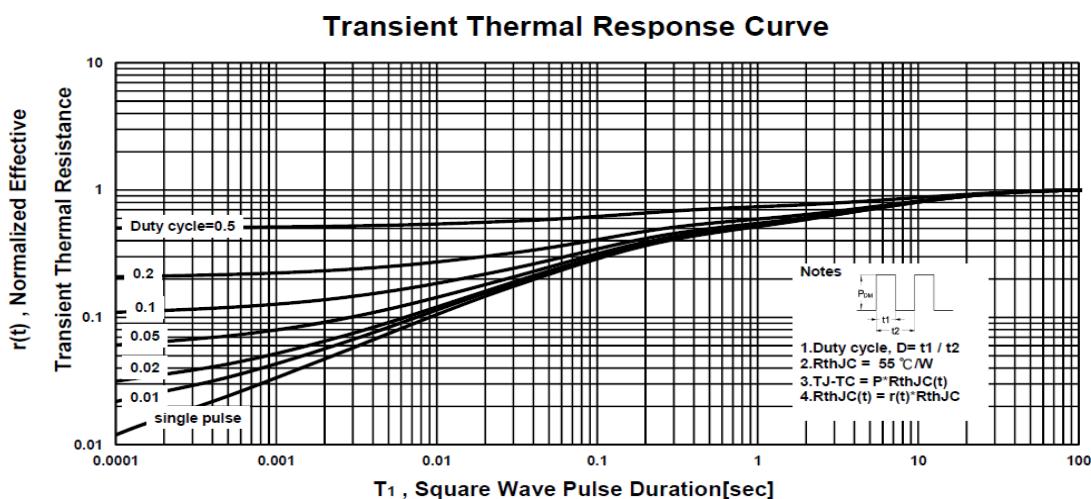
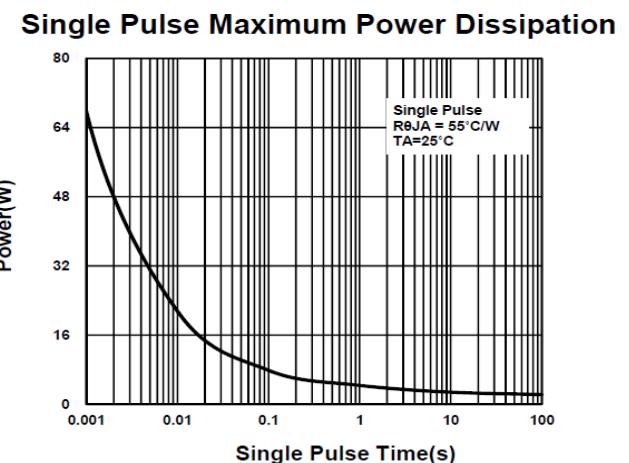
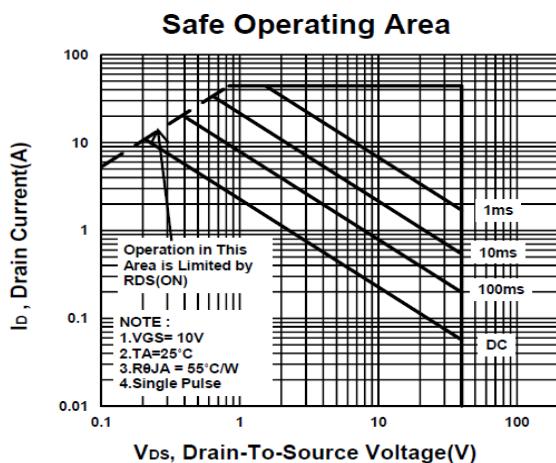
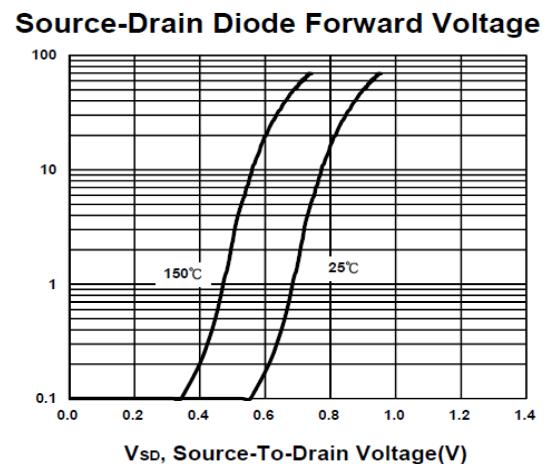
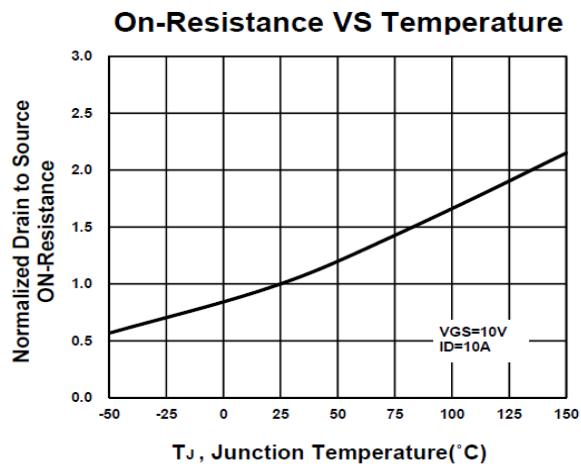
**On-Resistance VS Gate-To-Source**



**On-Resistance VS Drain Current**



## PV6A6BA N-Channel Enhancement Mode MOSFET



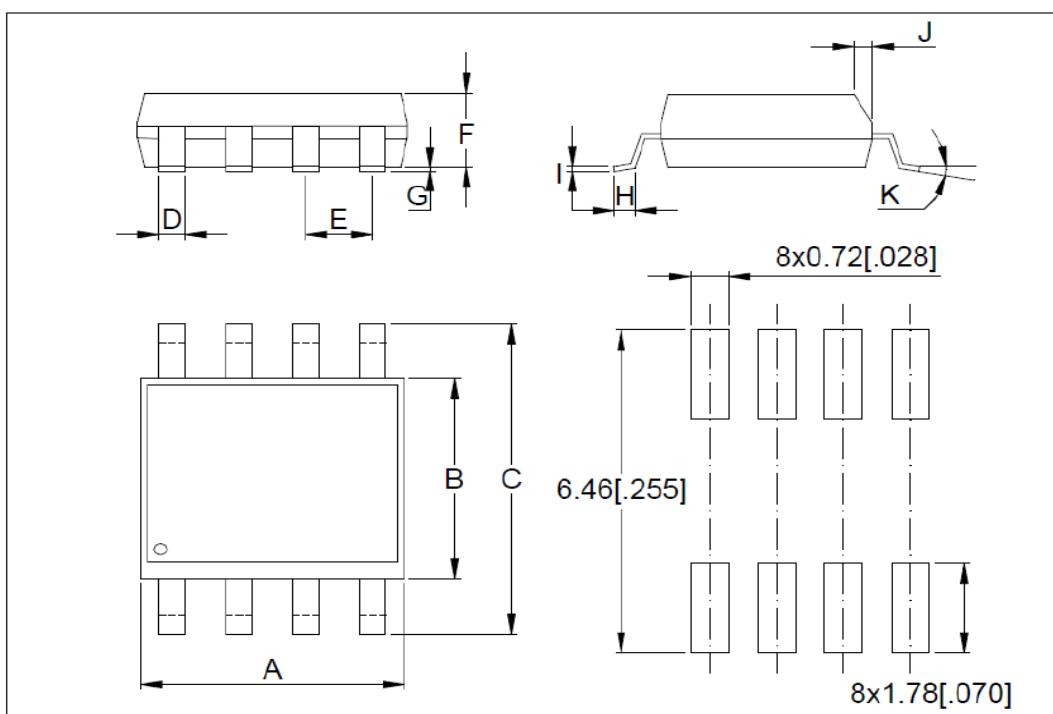
## PV6A6BA

### N-Channel Enhancement Mode MOSFET

#### Package Dimension

#### SOP-8 MECHANICAL DATA

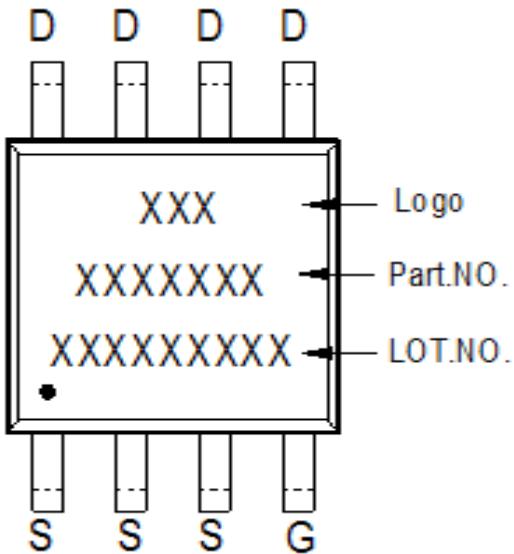
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				



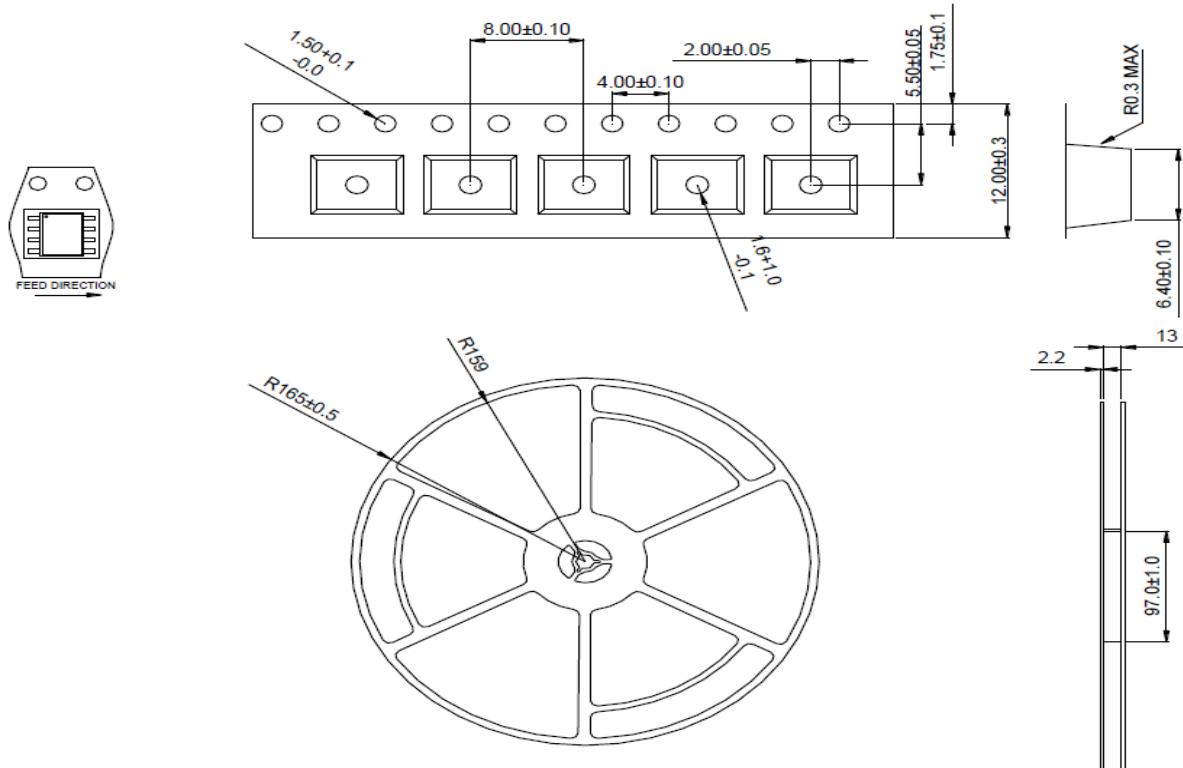
## PV6A6BA

### N-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 2500pcs/Reel

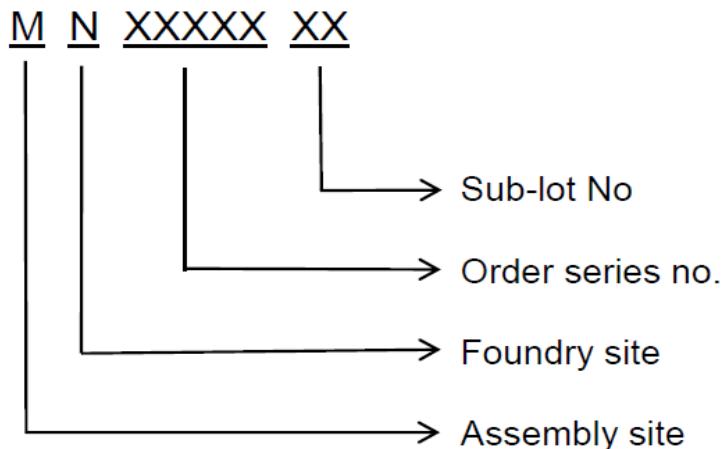


## PV6A6BA

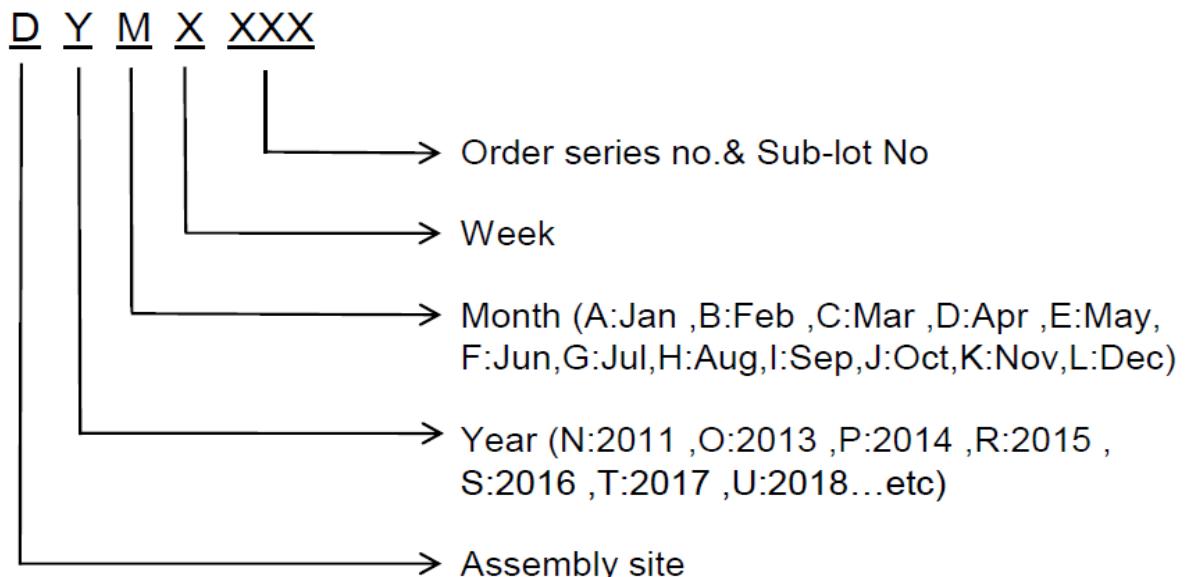
### N-Channel Enhancement Mode MOSFET

#### C. Lot No.&Date Code rule

##### 1. Lot No.



##### 2. Date Code



## PV6A6BA N-Channel Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm	
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)	
3	U-NIKC	Height: 4 mm	
4	Package	Height: 2 mm	
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12	
6	Device	Height: 3 mm (Max: 16 Digit)	
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot	
8	D/C	Height: 3 mm (Max: 7 Digit)	
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed	
10	RoHS label	<b>RoHS</b> long axis: 12 mm      minor axis: 6 mm bottom color: White Font color: Black      Font style: Arial	
11	Halogen Free label	<b>G</b> Diameter: 10 mm      bottom color: Green Font color: Black      Font style: Arial	
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least	